



Material Content Data Sheet



Sales Product Name		IPP076N15N5		Issued		19. July 2018		
MA#		MA001327310						
Package		PG-TO220-3-1		Weight*		2046.53 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.421	0.22	0.22	2160	2160
leadframe	non noble metal	iron	7439-89-6	0.816	0.04		399	
	inorganic material	phosphorus	7723-14-0	0.245	0.01		120	
	non noble metal	copper	7440-50-8	815.335	39.85	39.90	398398	398918
wire	non noble metal	aluminium	7429-90-5	99.014	4.84	4.84	48382	48382
encapsulation	organic material	carbon black	1333-86-4	7.662	0.37		3744	
	plastics	epoxy resin	-	84.283	4.12		41183	
	inorganic material	silicondioxide	60676-86-0	418.859	20.47	24.96	204668	249595
leadfinish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10487	10487
plating	non noble metal	nickel	7440-02-0	0.244	0.01		119	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	1	119
solder	noble metal	silver	7440-22-4	0.099	0.00		48	
	non noble metal	tin	7440-31-5	0.079	0.00		39	
	non noble metal	lead	7439-92-1	3.776	0.18	0.18	1845	1932
heatspreader	non noble metal	iron	7439-89-6	0.590	0.03		288	
	inorganic material	phosphorus	7723-14-0	0.177	0.01		87	
	non noble metal	copper	7440-50-8	589.466	28.80	28.84	288032	288407
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com